



APTEP1.40CP2DC (formerly APTLTD.40CP2DC)

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants : Gerald A. Hutchinson, et. al  
Appl. No. : 10/788,905  
Filed : February 26, 2004  
For : PREFORM MOLDS  
INCORPORATING HIGH HEAT  
CONDUCTIVITY MATERIAL  
Examiner : Timothy W. Heitbrink  
Group Art Unit : 1722

**RESPONSE TO AUGUST 1, 2006 OFFICE ACTION**

Mail Stop Amendment  
U.S. Patent and Trademark Office  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This Response is being filed after the Office Action mailed August 1, 2006 ("Office Action"). Applicants request the Examiner to reconsider the above-identified patent application in view of the following remarks.

**Listing of Claims** begins on page 2 of this paper.

**Remarks** begin on page 6 of this paper.